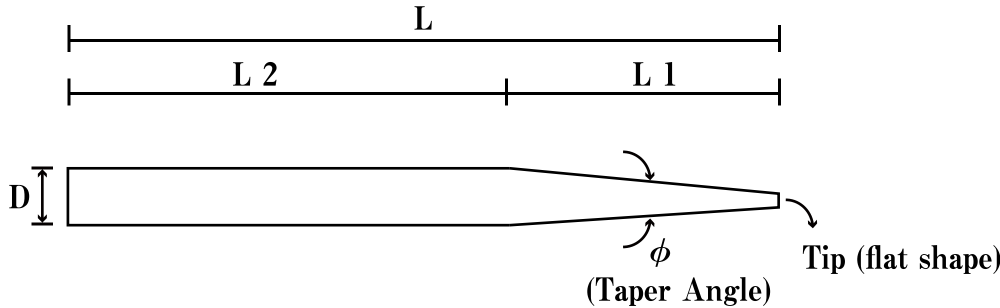
Processing Details of Ultra fine Wire into a Needle shape

Specs. of Probe Needle for Semiconductor Test

(1) For Cantilever Type & Vertical Contact Probe Card



- **Material**
  Ag-Pd-Cu alloy, P7 (Paliney 7),
  ReW (Rhenium-Tungsten), W (Tungsten) etc.
  Any material can be processed.

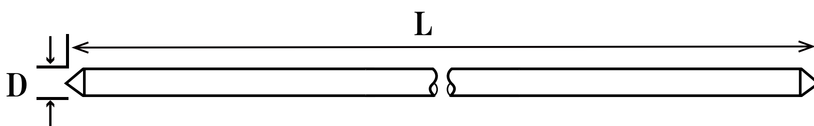
- **Total Length (L)**
  30mm - 120mm or so

- **Wire Diameter (D)**
  ϕ0.05mm～0.30mm

- **Tip Diameter**
  ϕ0.003mm - 0.012mm (tolerance: ±0.001 mm)

- **Taper Length (L1)**
  Up to 40 times of Wire Diameter (D)

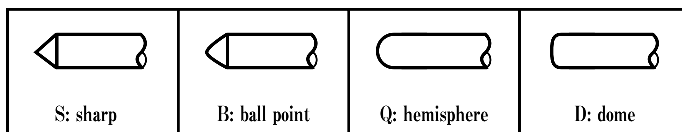
(2) Wire Probe (MEMS type)



- **Material**
  Rh (Rhodium), Ag-Pa-Cu alloy, P7 (Paliney 7),
  ReW (Rhenium-Tungsten), W (Tungsten) etc.
  Any material can be processed.

- **Total Length (L)**
  3.5mm～20mm

- **Tip Shape**



- **Tip Angle**
  30° ～ 60°
  60°

- **Wire Diameter (D)**
  ϕ0.02mm～0.08mm